Sangsun Yang

List of Publications by Year
in descending order

Source: https://exaly.com/author-pdf/6789310/publications.pdf

Version: 2024-02-01

9	103	6	8
papers	citations	h-index	g-index
		1478505	1588992

9	9	9	79
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Fabrication of pre-alloyed Alâ€“Li powders with high Li content via thermal dehydrogenation of LiH and rapid solidification process. Materials and Design, 2016, 94, 159-165.	7.0	21
2	Oxidation resistant effects of Ag2S in Snâ€“Agâ€“Al solder: A mechanism for higher electrical conductivity and less whisker growth. Corrosion Science, 2016, 105, 25-35.	6.6	19
3	Microstructure and mechanical behavior of low-melting point Bi-Sn-In solder joints. Electronic Materials Letters, 2017, 13, 420-426.	2.2	15
4	Thermo-mechanical evolution of ternary Biâ€“Snâ€“In solder micropowders and nanoparticles reflowed on a flexible PET substrate. Applied Surface Science, 2017, 415, 28-34.	6.1	14
5	Preparation of Property-Controlled Bi-Based Solder Powders by a Ball-Milling Process. Metals, 2016, 6, 74.	2.3	13
6	Employment of roll-offset printing for fabrication of solder bump arrays: Harnessing the rheological properties of lead-free solder pastes using particle size distribution. Microelectronic Engineering, 2016, 164, 128-134.	2.4	13
7	Low Melting Temperature Solder Materials for Use in Flexible Microelectronic Packaging Applications. , 0, , .		3
8	Microstructure and mechanical properties of carbon-bearing ultrahigh-strength high Co-Ni Steel (AerMet 340) fabricated via laser powder bed fusion. Materialia, 2021, 20, 101244.	2.7	3
9	Reduced Electrical Resistivity of Ternary Solder Alloy of Tin–Copper–Sulfur: An Anti-Oxidative Role of Sulfur in Binary Solder Alloy of Tin–Copper. Materials Transactions, 2014, 55, 1513-1516.	1.2	2